

BAT54H

Schottky barrier single diode in small SOD123F package

25 July 2012

Product data sheet

1. Product profile

1.1 General description

Planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a SOD123F small and flat lead Surface-Mounted Device (SMD) plastic package.

1.2 Features and benefits

- Low forward voltage
- Low capacitance
- AEC-Q101 qualified

1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Line termination
- Inverse-polarity protection



1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current		-	-	200	mA
V_R	reverse voltage		-	-	30	V
V_F	forward voltage	$I_F = 10 \text{ mA}$; pulsed; $t_p \leq 300 \text{ } \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ } ^\circ\text{C}$	-	-	400	mV

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode ^[1]	 SOD123F	 K A aaa-003679
2	A	anode		

[1] The marking bar indicates the cathode.



3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAT54H	SOD123F	plastic surface-mounted package; 2 leads	SOD123F

4. Marking

Table 4. Marking codes

Type number	Marking code
BAT54H	AG

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	30	V
I_F	forward current		-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
I_{FSM}	non-repetitive peak forward current	$t_p \leq 10$ ms; $T_{j(\text{init})} = 25$ °C	-	600	mA
P_{tot}	total power dissipation	$T_{\text{amb}} = 25$ °C	[1]	375	mW
T_j	junction temperature		-	125	°C
T_{amb}	ambient temperature		-65	125	°C
T_{stg}	storage temperature		-65	150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{\text{th}(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	330	K/W
$R_{\text{th}(j-sp)}$	thermal resistance from junction to solder point		[2]	-	70	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Soldering point of cathode tab.

7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 0.1 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	240	mV
		$I_F = 1 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	320	mV
		$I_F = 10 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	400	mV
		$I_F = 30 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	500	mV
		$I_F = 100 \text{ mA}$; pulsed; $t_p \leq 300 \mu\text{s}$; $\delta \leq 0.02$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	800	mV
I_R	reverse current	$V_R = 25 \text{ V}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	-	2	μA
C_d	diode capacitance	$f = 1 \text{ MHz}$; $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$; $V_R = 1 \text{ V}$	-	-	10	pF

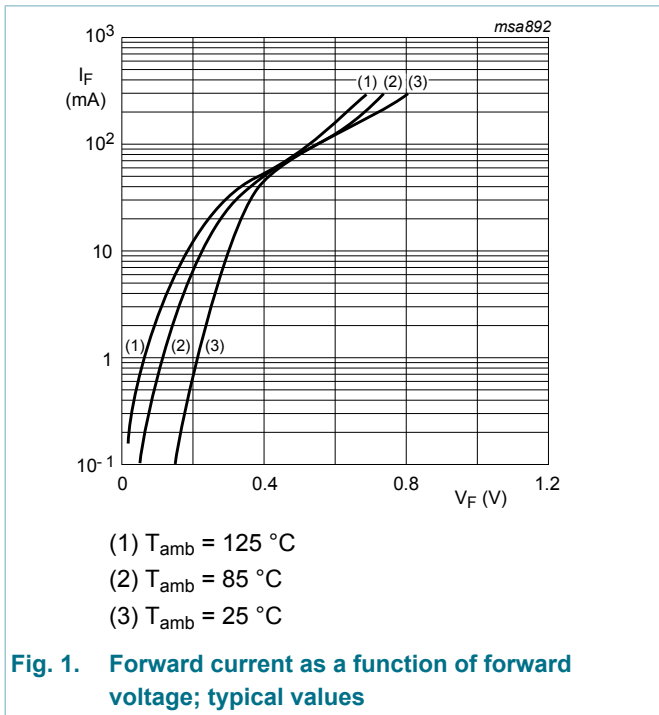


Fig. 1. Forward current as a function of forward voltage; typical values

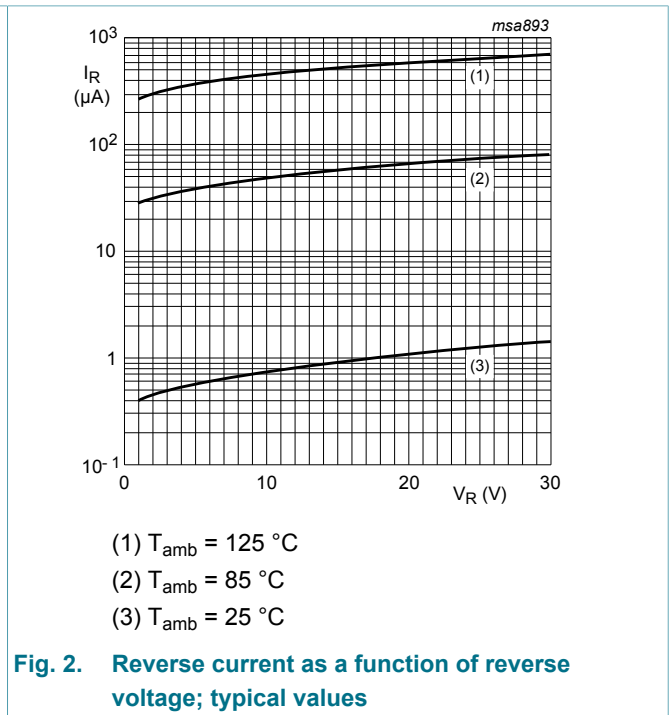
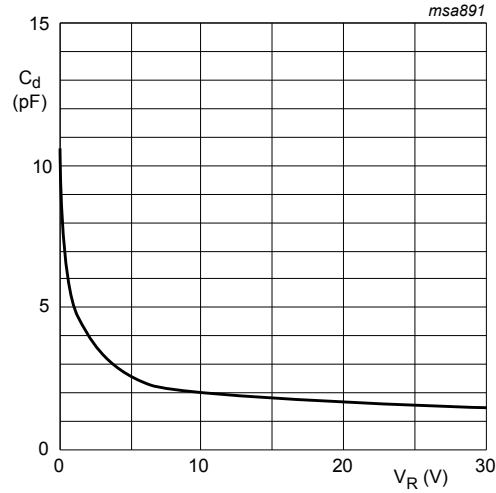


Fig. 2. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig. 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

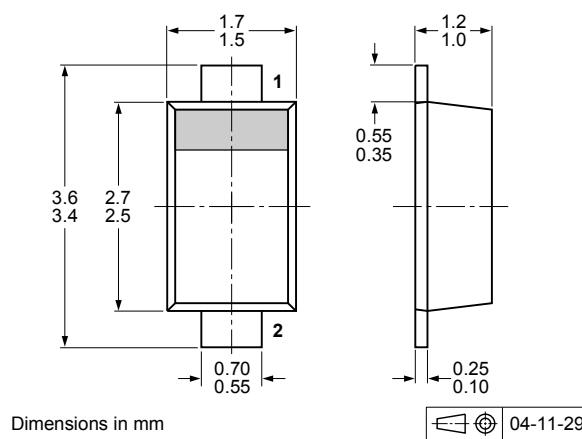


Fig. 4. SOD123F

10. Soldering

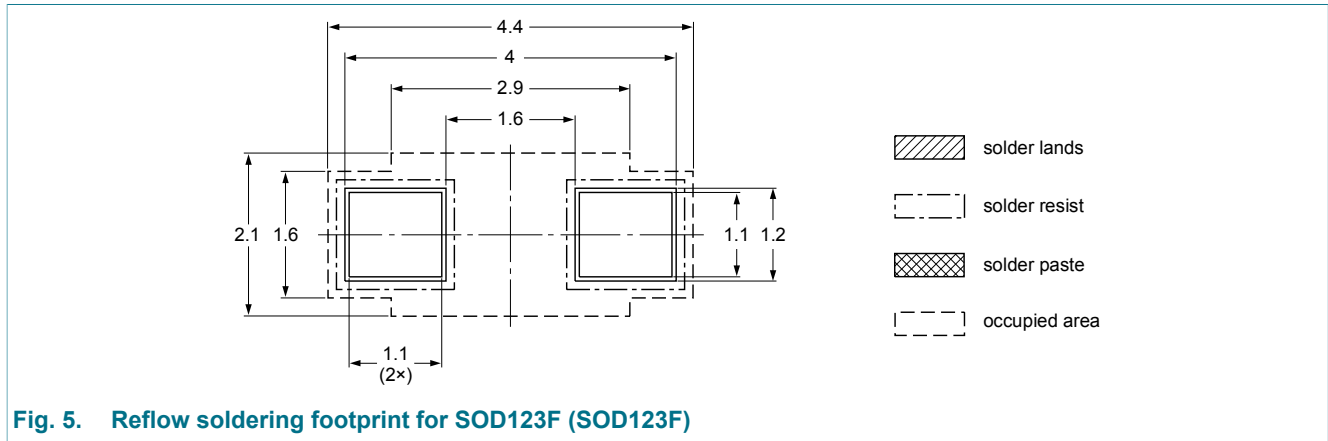


Fig. 5. Reflow soldering footprint for SOD123F (SOD123F)

11. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
BAT54H v.3	20120725	Product data sheet	-	BAT54H v.2
Modifications:	<ul style="list-style-type: none"> The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Section "Test information" added 			
BAT54H v.2	20100128	Product data sheet	-	BAT54H v.1
BAT54H v.1	20050407	Product data sheet	-	

12. Legal information

12.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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